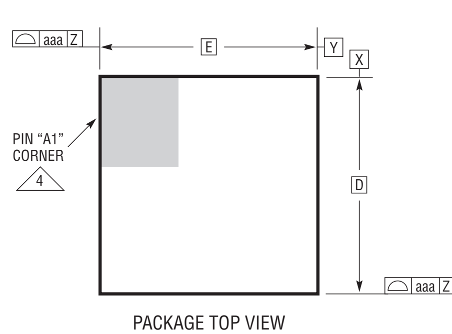
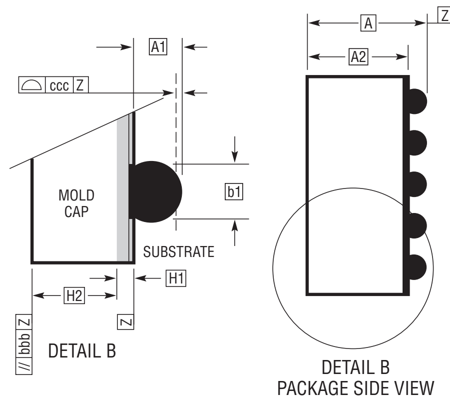
BGA Package
25-Lead (6.25mm × 6.25mm × 2.42mm)
(Reference LTC DWG # 05-08-1502 Rev Ø)

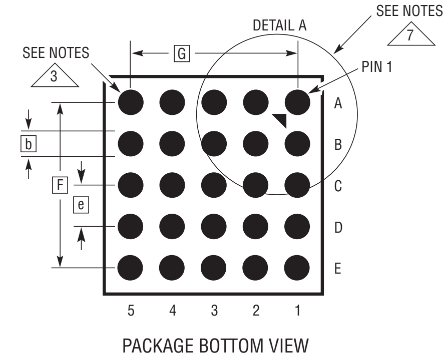


PACKAGE TOP VIEW

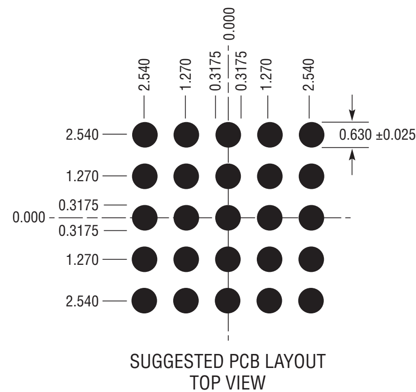


DETAIL B

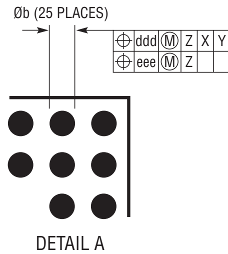
DETAIL B
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



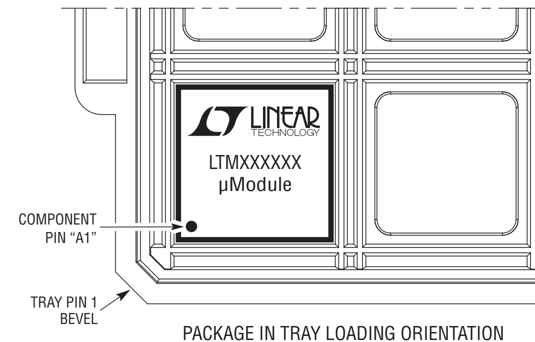
SUGGESTED PCB LAYOUT
TOP VIEW



DETAIL A

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	2.22	2.42	2.62	
A1	0.50	0.60	0.70	
A2	1.72	1.82	1.92	
b	0.60	0.75	0.90	
b1	0.60	0.63	0.66	
D		6.25		
E		6.25		
e		1.27		
F		5.08		
G		5.08		
H1	0.27	0.32	0.37	
H2	1.45	1.50	1.55	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	
TOTAL NUMBER OF BALLS: 25				

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JESD MS-028 AND JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
7. ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION

BGA 25 0515 REV Ø